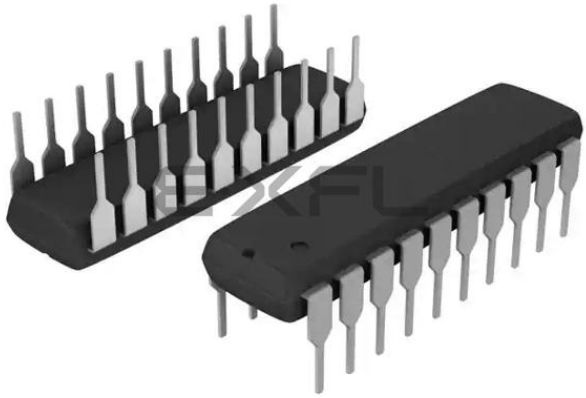

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What is "Embedded - Microcontrollers"?

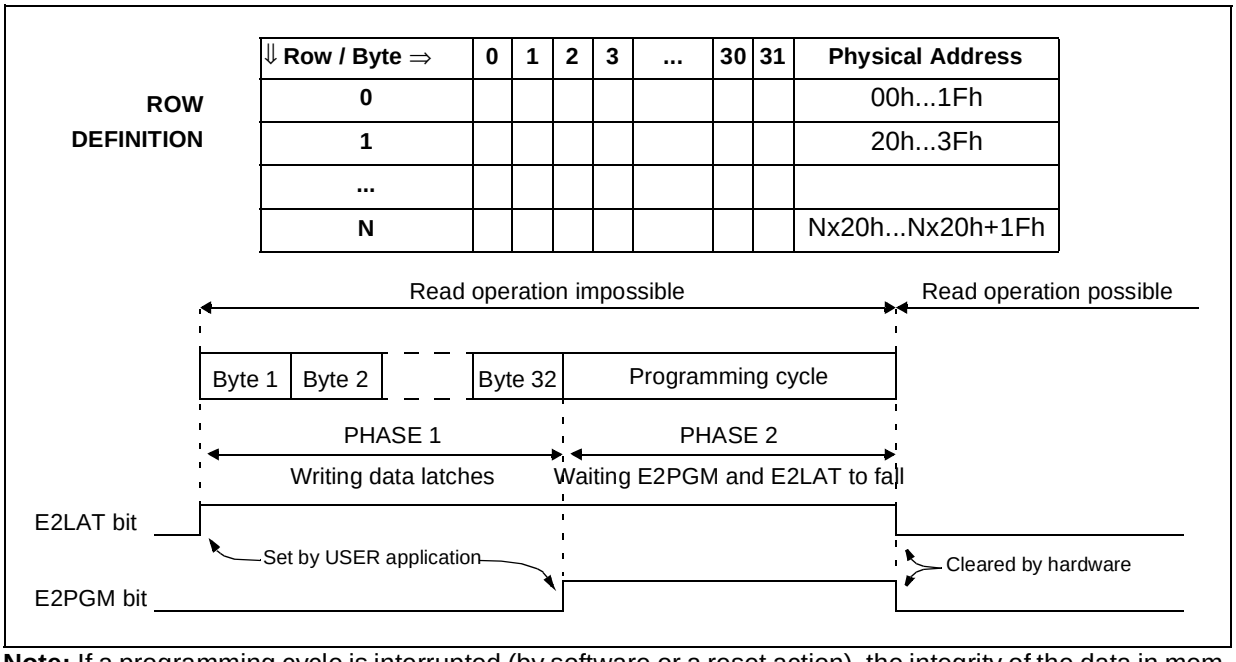
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	ST7
Core Size	8-Bit
Speed	16MHz
Connectivity	SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	15
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 5.5V
Data Converters	A/D 7x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	20-DIP (0.300", 7.62mm)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/st7flite19f1b6

DATA EEPROM (Cont'd)

Figure 8. Data E^2PROM Write Operation



Note: If a programming cycle is interrupted (by software or a reset action), the integrity of the data in memory is not guaranteed.

7.6 SYSTEM INTEGRITY MANAGEMENT (SI)

The System Integrity Management block contains the Low voltage Detector (LVD) and Auxiliary Voltage Detector (AVD) functions. It is managed by the SICSR register.

7.6.1 Low Voltage Detector (LVD)

The Low Voltage Detector function (LVD) generates a static reset when the V_{DD} supply voltage is below a $V_{IT-(LVD)}$ reference value. This means that it secures the power-up as well as the power-down keeping the ST7 in reset.

The $V_{IT-(LVD)}$ reference value for a voltage drop is lower than the $V_{IT+(LVD)}$ reference value for power-on in order to avoid a parasitic reset when the MCU starts running and sinks current on the supply (hysteresis).

The LVD Reset circuitry generates a reset when V_{DD} is below:

– $V_{IT+(LVD)}$when V_{DD} is rising

– $V_{IT-(LVD)}$ when V_{DD} is falling

The LVD function is illustrated in Figure 17.

The voltage threshold can be configured by option byte to be low, medium or high.

Provided the minimum V_{DD} value (guaranteed for the oscillator frequency) is above $V_{IT-(LVD)}$, the MCU can only be in two modes:

– under full software control

– in static safe reset

In these conditions, secure operation is always ensured for the application without the need for external reset hardware.

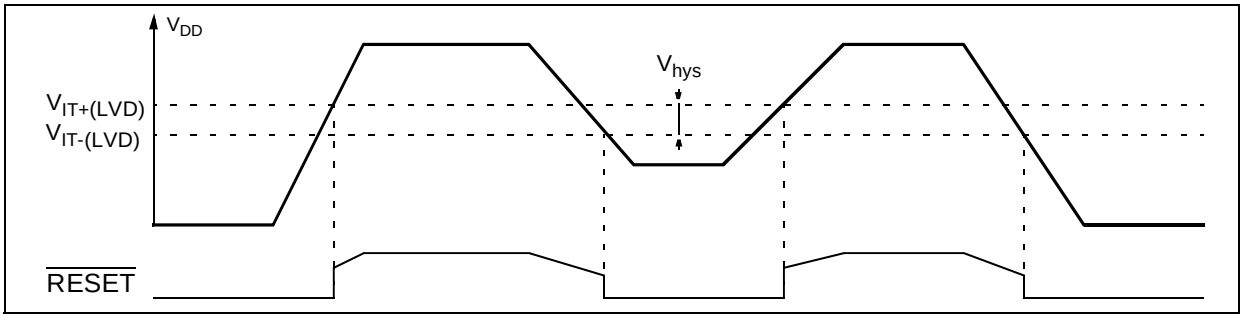
During a Low Voltage Detector Reset, the $\overline{\text{RESET}}$ pin is held low, thus permitting the MCU to reset other devices.

Notes:

The LVD allows the device to be used without any external RESET circuitry.

The LVD is an optional function which can be selected by option byte.

Figure 17. Low Voltage Detector vs Reset



9 POWER SAVING MODES

9.1 INTRODUCTION

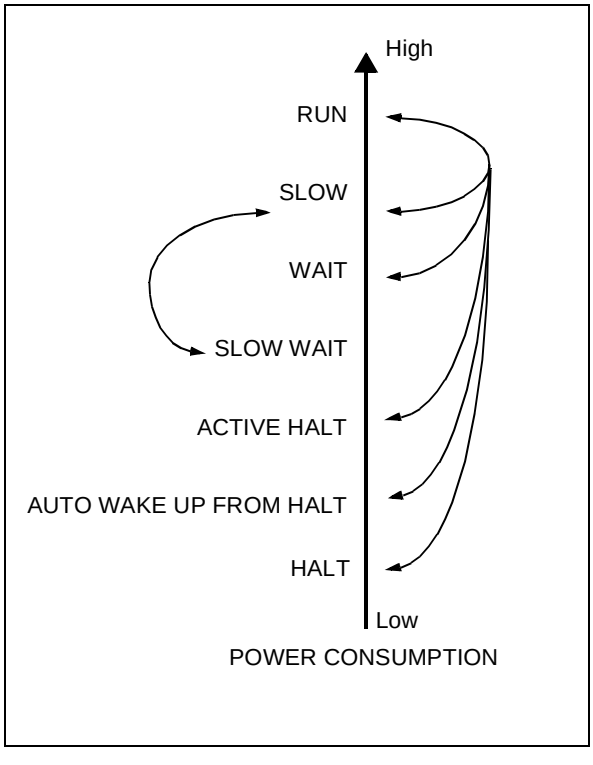
To give a large measure of flexibility to the application in terms of power consumption, five main power saving modes are implemented in the ST7 (see Figure 21):

- Slow
- Wait (and Slow-Wait)
- Active Halt
- Auto Wake up From Halt (AWUFH)
- Halt

After a RESET the normal operating mode is selected by default (RUN mode). This mode drives the device (CPU and embedded peripherals) by means of a master clock which is based on the main oscillator frequency divided or multiplied by 2 (f_{OSC2}).

From RUN mode, the different power saving modes may be selected by setting the relevant register bits or by calling the specific ST7 software instruction whose action depends on the oscillator status.

Figure 21. Power Saving Mode Transitions



9.2 SLOW MODE

This mode has two targets:

– To reduce power consumption by decreasing the internal clock in the device,

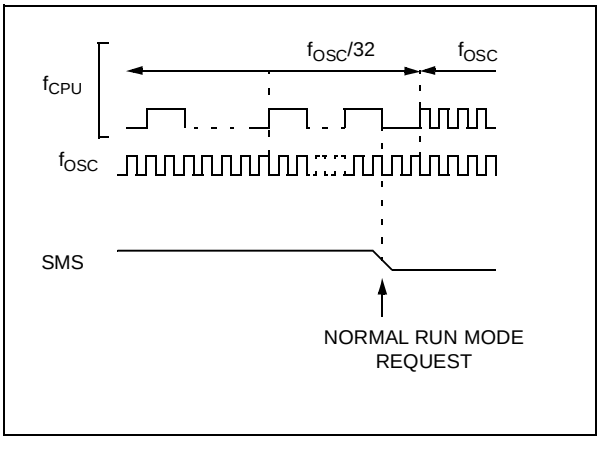
– To adapt the internal clock frequency (f_{CPU}) to the available supply voltage.

SLOW mode is controlled by the SMS bit in the MCCSR register which enables or disables Slow mode.

In this mode, the oscillator frequency is divided by 32. The CPU and peripherals are clocked at this lower frequency.

Note: SLOW-WAIT mode is activated when entering WAIT mode while the device is already in SLOW mode.

Figure 22. SLOW Mode Clock Transition



11 ON-CHIP PERIPHERALS

11.1 WATCHDOG TIMER (WDG)

11.1.1 Introduction

The Watchdog timer is used to detect the occurrence of a software fault, usually generated by external interference or by unforeseen logical conditions, which causes the application program to abandon its normal sequence. The Watchdog circuit generates an MCU reset on expiry of a programmed time period, unless the program refreshes the counter's contents before the T6 bit becomes cleared.

11.1.2 Main Features

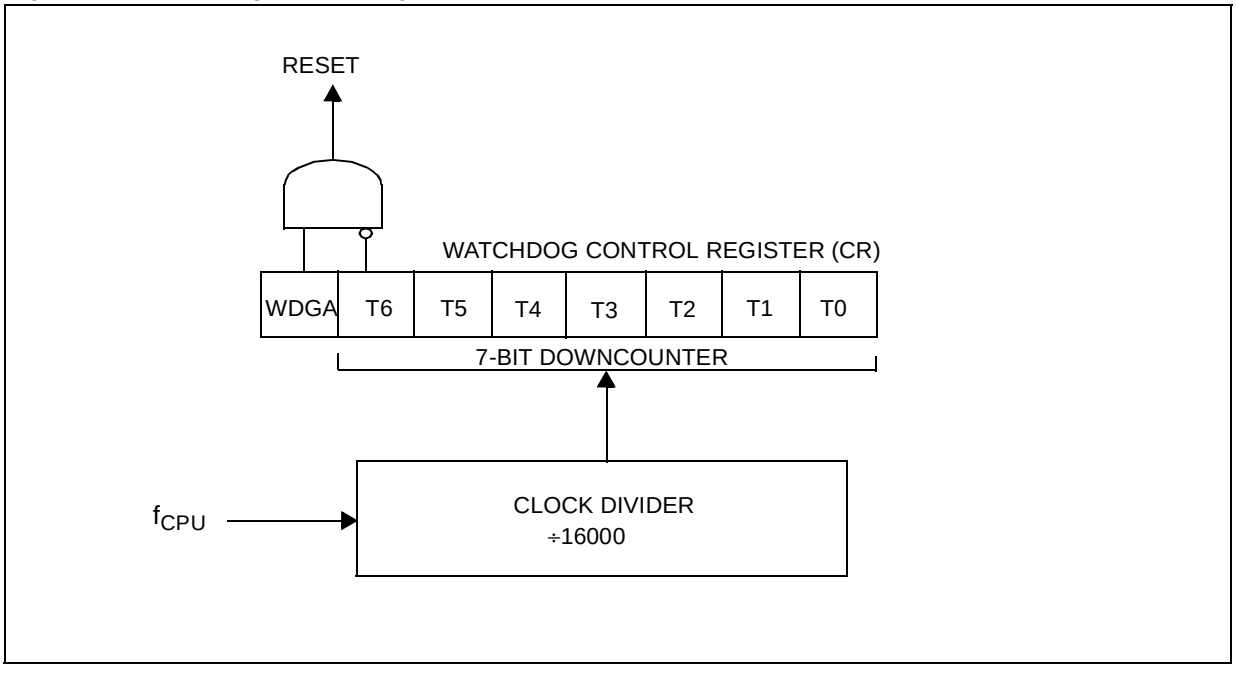
- Programmable free-running downcounter (64 increments of 16000 CPU cycles)
- Programmable reset
- Reset (if watchdog activated) when the T6 bit reaches zero
- Optional reset on HALT instruction (configurable by option byte)
- Hardware Watchdog selectable by option byte

11.1.3 Functional Description

The counter value stored in the CR register (bits T[6:0]), is decremented every 16000 machine cycles, and the length of the timeout period can be programmed by the user in 64 increments.

If the watchdog is activated (the WDGA bit is set) and when the 7-bit timer (bits T[6:0]) rolls over from 40h to 3Fh (T6 becomes cleared), it initiates a reset cycle pulling low the reset pin for typically 36µs.

Figure 33. Watchdog Block Diagram



WATCHDOG TIMER (Cont'd)

The application program must write in the CR register at regular intervals during normal operation to prevent an MCU reset. This downcounter is free-running: it counts down even if the watchdog is disabled. The value to be stored in the CR register must be between FFh and C0h (see Table 12 .Watchdog Timing):

– The WDGA bit is set (watchdog enabled)

– The T6 bit is set to prevent generating an immediate reset

– The T[5:0] bits contain the number of increments which represents the time delay before the watchdog produces a reset.

Following a reset, the watchdog is disabled. Once activated it cannot be disabled, except by a reset.

The T6 bit can be used to generate a software reset (the WDGA bit is set and the T6 bit is cleared).

If the watchdog is activated, the HALT instruction will generate a Reset.

Table 12.Watchdog Timing

f_{CPU} = 8MHz		
WDG Counter Code	**min [ms]**	**max [ms]**
C0h	1	2
FFh	127	128

Notes:
1. The timing variation shown in Table 12 is due to the unknown status of the prescaler when writing to the CR register.
2. The number of CPU clock cycles applied during the RESET phase (256 or 4096) must be taken into account in addition to these timings.

11.1.4 Hardware Watchdog Option

If Hardware Watchdog is selected by option byte, the watchdog is always active and the WDGA bit in the CR is not used.

Refer to the Option Byte description in section 15 on page 123.

11.1.4.1 Using Halt Mode with the WDG (WDGHALT option)

If Halt mode with Watchdog is enabled by option byte (No watchdog reset on HALT instruction), it is recommended before executing the HALT instruction to refresh the WDG counter, to avoid an unexpected WDG reset immediately after waking up the microcontroller. Same behavior in active-halt mode.

WATCHDOG TIMER (Cont'd)

11.1.5 Interrupts

None.

11.1.6 Register Description

CONTROL REGISTER (CR)

Read/Write

Reset Value: 0111 1111 (7Fh)

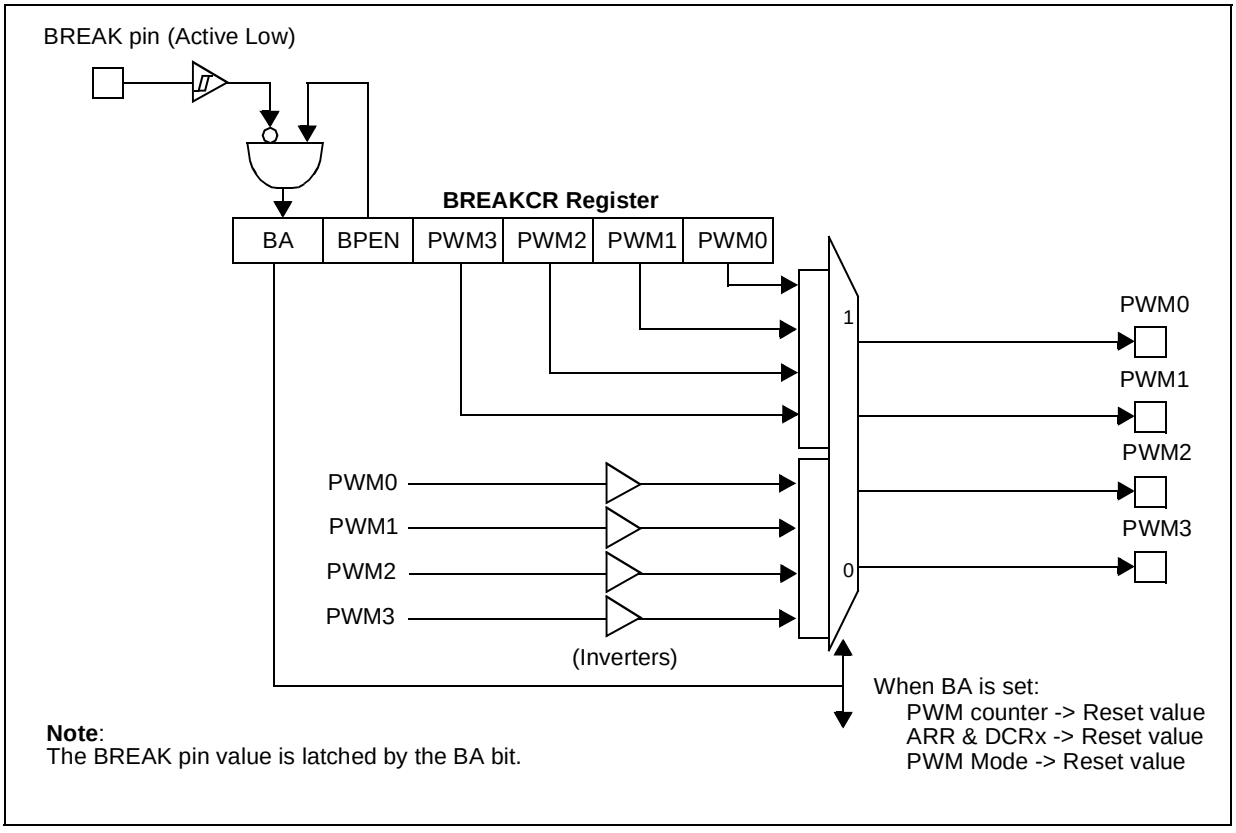
7							0
WDGA	T6	T5	T4	T3	T2	T1	T0

Bit 7 = **WDGA** *Activation bit*.
This bit is set by software and only cleared by hardware after a reset. When WDGA = 1, the watchdog can generate a reset.
0: Watchdog disabled
1: Watchdog enabled

Note: This bit is not used if the hardware watchdog option is enabled by option byte.

Bit 6:0 = **T[6:0]** *7-bit timer (MSB to LSB).*
These bits contain the decremented value. A reset is produced when it rolls over from 40h to 3Fh (T6 becomes cleared).

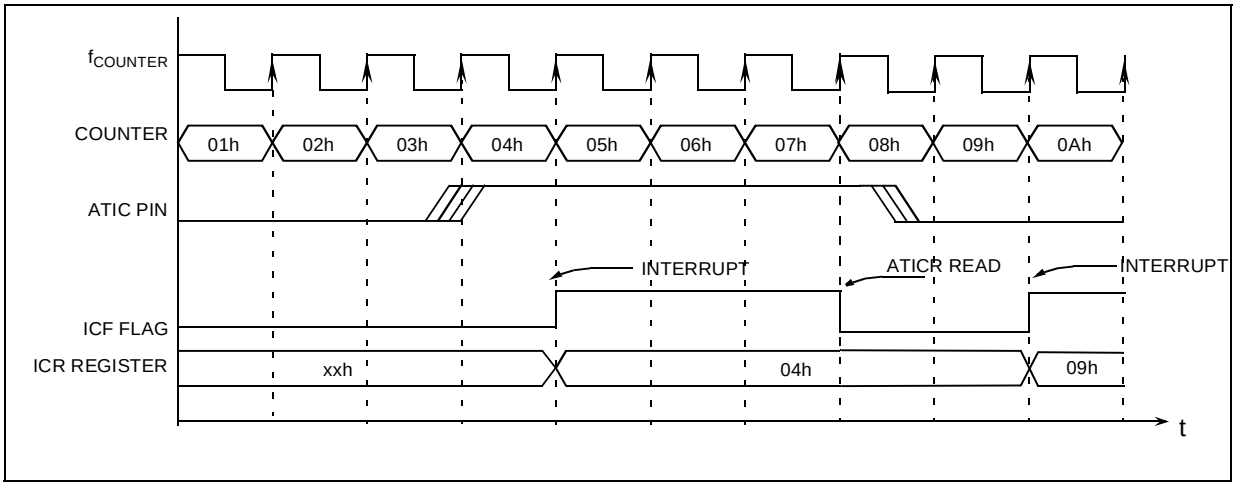
Figure 38. Block Diagram of Break Function



11.2.3.1 Input Capture

The 12-bit ATICR register is used to latch the value of the 12-bit free running upcounter after a rising or falling edge is detected on the ATIC pin. When an input capture occurs, the ICF bit is set and the ATICR register contains the value of the free running upcounter. An IC interrupt is generated if the ICIE bit is set. The ICF bit is reset by reading the ATICR register when the ICF bit is set. The ATICR is a read only register and always contains the free running upcounter value which corresponds to the most recent input capture. Any further input capture is inhibited while the ICF bit is set.

Figure 39. Input Capture Timing Diagram



12-BIT AUTORELOAD TIMER (Cont'd)

AUTORELOAD REGISTER (ATRH)
Read / Write
Reset Value: 0000 0000 (00h)

15							8
0	0	0	0	ATR11	ATR10	ATR9	ATR8

AUTORELOAD REGISTER (ATRL)
Read / Write
Reset Value: 0000 0000 (00h)

7							0
ATR7	ATR6	ATR5	ATR4	ATR3	ATR2	ATR1	ATR0

Bits 11:0 = **ATR[11:0]** *Autoreload Register.*
This is a 12-bit register which is written by software. The ATR register value is automatically loaded into the upcounter when an overflow occurs. The register value is used to set the PWM frequency.

PWM OUTPUT CONTROL REGISTER (PWMCR)
Read/Write
Reset Value: 0000 0000 (00h)

7							0
0	OE3	0	OE2	0	OE1	0	OE0

Bits 7:0 = **OE[3:0]** *PWMx output enable*.
These bits are set and cleared by software and cleared by hardware after a reset.
0: PWM mode disabled. PWMx Output Alternate Function disabled (I/O pin free for general purpose I/O)
1: PWM mode enabled

PWMx CONTROL STATUS REGISTER (PWMxCSR)
Read / Write
Reset Value: 0000 0000 (00h)

7	6						0
0	0	0	0	0	0	OPx	CMPFx

Bits 7:2= Reserved, must be kept cleared.

Bit 1 = **OPx** *PWMx Output Polarity.*
This bit is read/write by software and cleared by hardware after a reset. This bit selects the polarity of the PWM signal.
0: The PWM signal is not inverted.
1: The PWM signal is inverted.

Bit 0 = **CMPFx** PWMx *Compare Flag.*
This bit is set by hardware and cleared by software by reading the PWMxCSR register. It indicates that the upcounter value matches the DCRx register value.
0: Upcounter value does not match DCR value.
1: Upcounter value matches DCR value.

BREAK CONTROL REGISTER (BREAKCR)
Read/Write
Reset Value: 0000 0000 (00h)

7							0
0	0	BA	BPEN	PWM3	PWM2	PWM1	PWM0

Bits 7:6 = Reserved. Forced by hardware to 0.

Bit 5 = **BA** *Break Active.*
This bit is read/write by software, cleared by hardware after reset and set by hardware when the BREAK pin is low. It activates/deactivates the Break function.
0: Break not active
1: Break active

SERIAL PERIPHERAL INTERFACE (Cont'd)

11.4.5.4 Single Master and Multimaster Configurations

There are two types of SPI systems:

– Single Master System

– Multimaster System

Single Master System

A typical single master system may be configured, using a device as the master and four devices as slaves (see Figure 48).

The master device selects the individual slave devices by using four pins of a parallel port to control the four $\overline{SS}$ pins of the slave devices.

The $\overline{SS}$ pins are pulled high during reset since the master device ports will be forced to be inputs at that time, thus disabling the slave devices.

Note: To prevent a bus conflict on the MISO line the master allows only one active slave device during a transmission.

For more security, the slave device may respond to the master with the received data byte. Then the master will receive the previous byte back from the slave device if all MISO and MOSI pins are connected and the slave has not written to its SPIDR register.

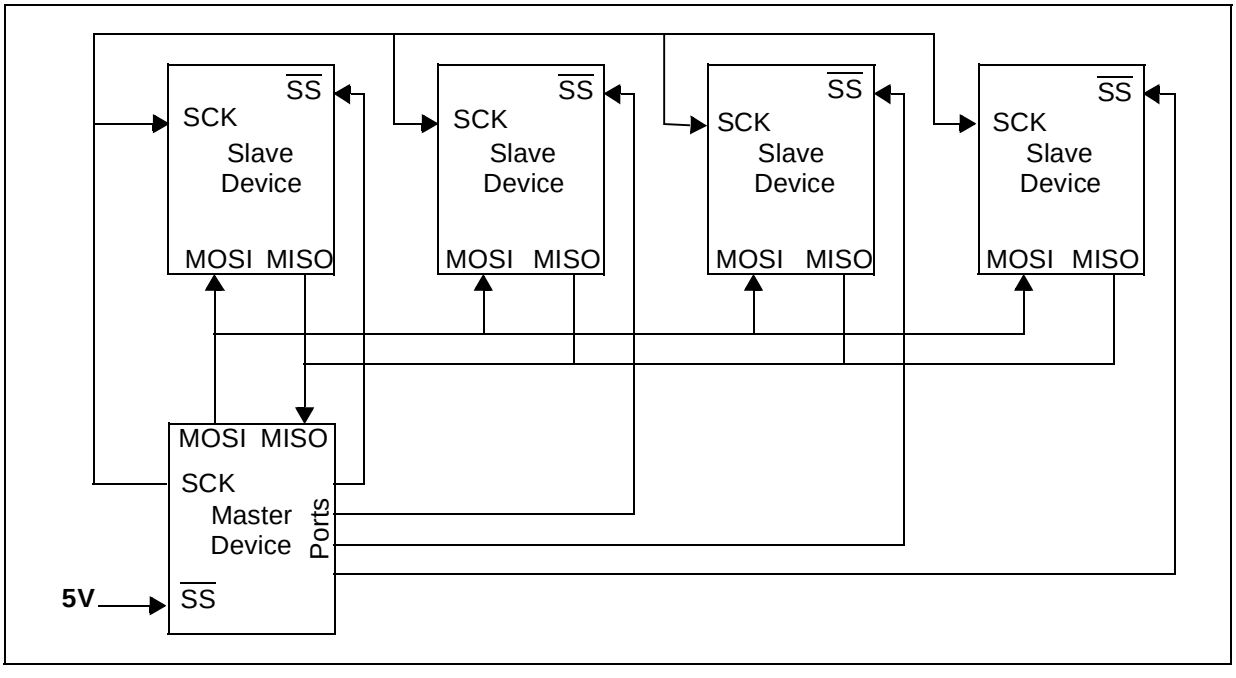
Other transmission security methods can use ports for handshake lines or data bytes with command fields.

Multi-Master System

A multi-master system may also be configured by the user. Transfer of master control could be implemented using a handshake method through the I/O ports or by an exchange of code messages through the serial peripheral interface system.

The multi-master system is principally handled by the MSTR bit in the SPICR register and the MODF bit in the SPICSR register.

Figure 48. Single Master / Multiple Slave Configuration



11.5 10-BIT A/D CONVERTER (ADC)

11.5.1 Introduction

The on-chip Analog to Digital Converter (ADC) peripheral is a 10-bit, successive approximation converter with internal sample and hold circuitry. This peripheral has up to 7 multiplexed analog input channels (refer to device pin out description) that allow the peripheral to convert the analog voltage levels from up to 7 different sources.

The result of the conversion is stored in a 10-bit Data Register. The A/D converter is controlled through a Control/Status Register.

11.5.2 Main Features

- 10-bit conversion
- Up to 7 channels with multiplexed input
- Linear successive approximation
- Data register (DR) which contains the results
- Conversion complete status flag
- On/off bit (to reduce consumption)

The block diagram is shown in Figure 49.

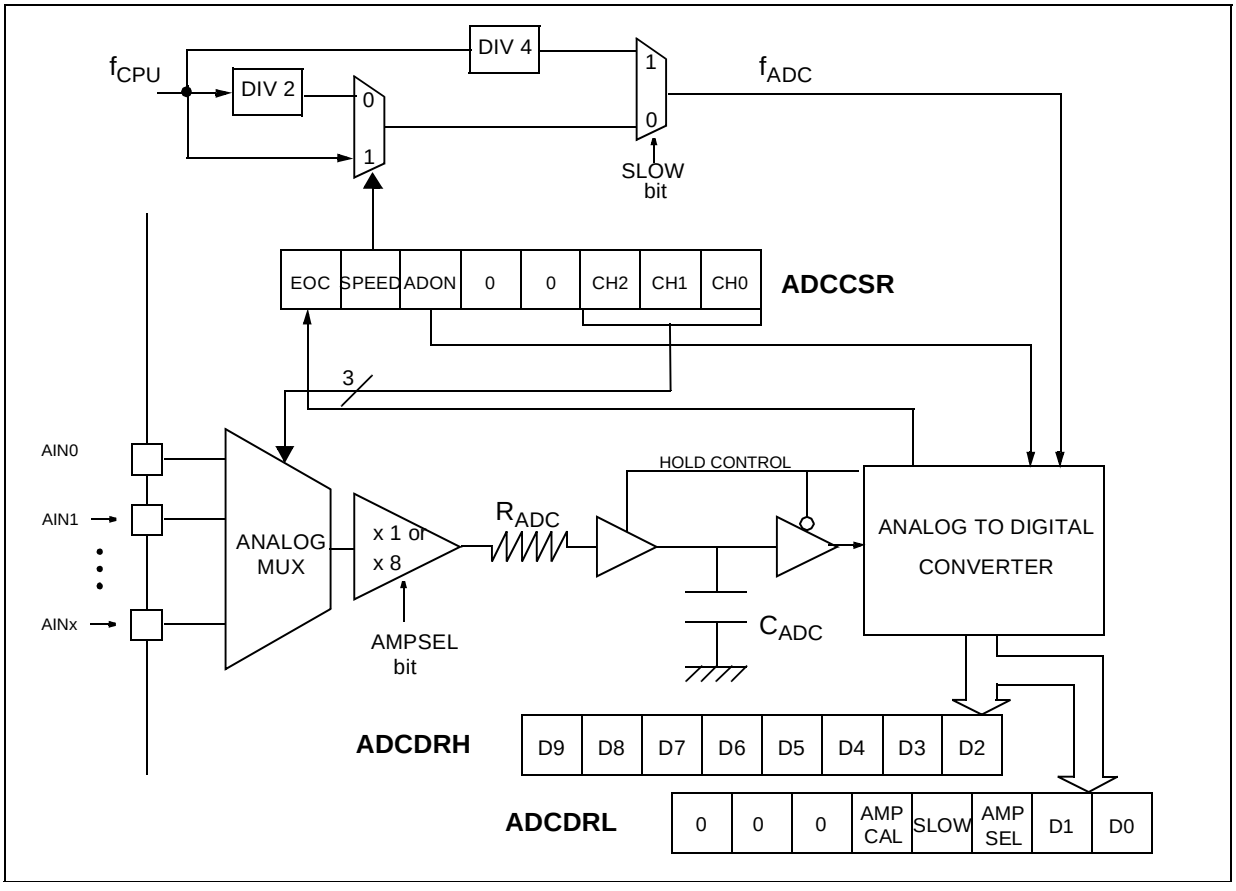
11.5.3 Functional Description

11.5.3.1 Analog Power Supply

V_{DDA} and V_{SSA} are the high and low level reference voltage pins. In some devices (refer to device pin out description) they are internally connected to the V_{DD} and V_{SS} pins.

Conversion accuracy may therefore be impacted by voltage drops and noise in the event of heavily loaded or badly decoupled power supply lines.

Figure 49. ADC Block Diagram



10-BIT A/D CONVERTER (ADC) (Cont'd)

11.5.3.2 Input Voltage Amplifier

The input voltage can be amplified by a factor of 8 by enabling the AMPSEL bit in the ADCDRL register.

When the amplifier is enabled, the input range is 0V to $V_{DD}/8$.

For example, if V_{DD} = 5V, then the ADC can convert voltages in the range 0V to 430mV with an ideal resolution of 0.6mV (equivalent to 13-bit resolution with reference to a V_{SS} to V_{DD} range).

For more details, refer to the Electrical characteristics section.

Note: The amplifier is switched on by the ADON bit in the ADCCSR register, so no additional start-up time is required when the amplifier is selected by the AMPSEL bit.

11.5.3.3 Digital A/D Conversion Result

The conversion is monotonic, meaning that the result never decreases if the analog input does not and never increases if the analog input does not.

If the input voltage (V_{AIN}) is greater than V_{DDA} (high-level voltage reference) then the conversion result is FFh in the ADCDRH register and 03h in the ADCDRL register (without overflow indication).

If the input voltage (V_{AIN}) is lower than V_{SSA} (low-level voltage reference) then the conversion result in the ADCDRH and ADCDRL registers is 00 00h.

The A/D converter is linear and the digital result of the conversion is stored in the ADCDRH and ADCDRL registers. The accuracy of the conversion is described in the Electrical Characteristics Section.

R_{AIN} is the maximum recommended impedance for an analog input signal. If the impedance is too high, this will result in a loss of accuracy due to leakage and sampling not being completed in the alloted time.

11.5.3.4 A/D Conversion

The analog input ports must be configured as input, no pull-up, no interrupt. Refer to the «I/O ports» chapter. Using these pins as analog inputs does not affect the ability of the port to be read as a logic input.

In the ADCCSR register:

– Select the CS[2:0] bits to assign the analog channel to convert.

ADC Conversion mode

In the ADCCSR register:

Set the ADON bit to enable the A/D converter and to start the conversion. From this time on, the ADC performs a continuous conversion of the selected channel.

When a conversion is complete:

– The EOC bit is set by hardware.
– The result is in the ADCDR registers.

A read to the ADCDRH resets the EOC bit.

To read the 10 bits, perform the following steps:

1. Poll EOC bit
2. Read ADCDRL
3. Read ADCDRH. This clears EOC automatically.

To read only 8 bits, perform the following steps:

1. Poll EOC bit
2. Read ADCDRH. This clears EOC automatically.

11.5.4 Low Power Modes

Note: The A/D converter may be disabled by resetting the ADON bit. This feature allows reduced power consumption when no conversion is needed and between single shot conversions.

Mode	Description
WAIT	No effect on A/D Converter
HALT	A/D Converter disabled. After wakeup from Halt mode, the A/D Converter requires a stabilization time t_{STAB} (see Electrical Characteristics) before accurate conversions can be performed.

11.5.5 Interrupts

None.

12 INSTRUCTION SET

12.1 ST7 ADDRESSING MODES

The ST7 Core features 17 different addressing modes which can be classified in 7 main groups:

Addressing Mode	Example
Inherent	nop
Immediate	ld A,#$55
Direct	ld A,$55
Indexed	ld A,($55,X)
Indirect	ld A,([$55],X)
Relative	jrne loop
Bit operation	bset byte,#5

The ST7 Instruction set is designed to minimize the number of bytes required per instruction: To do so, most of the addressing modes may be subdivided in two sub-modes called long and short:

– Long addressing mode is more powerful because it can use the full 64 Kbyte address space, however it uses more bytes and more CPU cycles.

– Short addressing mode is less powerful because it can generally only access page zero (0000h - 00FFh range), but the instruction size is more compact, and faster. All memory to memory instructions use short addressing modes only (CLR, CPL, NEG, BSET, BRES, BTJT, BTJF, INC, DEC, RLC, RRC, SLL, SRL, SRA, SWAP)

The ST7 Assembler optimizes the use of long and short addressing modes.

Table 19. ST7 Addressing Mode Overview

Mode			Syntax	Destination/ Source	Pointer Address (Hex.)	Pointer Size (Hex.)	Length (Bytes)
Inherent			nop				+ 0
Immediate			ld A,#$55				+ 1
Short	Direct		ld A,$10	00..FF			+ 1
Long	Direct		ld A,$1000	0000..FFFF			+ 2
No Offset	Direct	Indexed	ld A,(X)	00..FF			+ 0 (with X register) + 1 (with Y register)
Short	Direct	Indexed	ld A,($10,X)	00..1FE			+ 1
Long	Direct	Indexed	ld A,($1000,X)	0000..FFFF			+ 2
Short	Indirect		ld A,[$10]	00..FF	00..FF	byte	+ 2
Long	Indirect		ld A,[$10.w]	0000..FFFF	00..FF	word	+ 2
Short	Indirect	Indexed	ld A,([$10],X)	00..1FE	00..FF	byte	+ 2
Long	Indirect	Indexed	ld A,([$10.w],X)	0000..FFFF	00..FF	word	+ 2
Relative	Direct		jrne loop	PC-128/PC+127[1)]			+ 1
Relative	Indirect		jrne [$10]	PC-128/PC+127[1)]	00..FF	byte	+ 2
Bit	Direct		bset $10,#7	00..FF			+ 1
Bit	Indirect		bset [$10],#7	00..FF	00..FF	byte	+ 2
Bit	Direct	Relative	btjt $10,#7,skip	00..FF			+ 2
Bit	Indirect	Relative	btjt [$10],#7,skip	00..FF	00..FF	byte	+ 3

Note 1. At the time the instruction is executed, the Program Counter (PC) points to the instruction following JRxx.

13.2 ABSOLUTE MAXIMUM RATINGS

Stresses above those listed as “absolute maximum ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device under these conditions is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

13.2.1 Voltage Characteristics

Symbol	Ratings	Maximum value	Unit
V_{DD} - V_{SS}	Supply voltage	7.0	V
V_{IN}	Input voltage on any pin [1) & 2)]	V_{SS}-0.3 to V_{DD}+0.3	
$V_{ESD(HBM)}$	Electrostatic discharge voltage (Human Body Model)	see section 13.7.3 on page 104	
$V_{ESD(MM)}$	Electrostatic discharge voltage (Machine Model)		

13.2.2 Current Characteristics

Symbol	Ratings	Maximum value	Unit
I_{VDD}	Total current into V_{DD} power lines (source) [3)]	150	mA
I_{VSS}	Total current out of V_{SS} ground lines (sink) [3)]	150	
I_{IO}	Output current sunk by any standard I/O and control pin	25	
	Output current sunk by any high sink I/O pin	50	
	Output current source by any I/Os and control pin	- 25	
$I_{INJ(PIN)}$ [2) & 4)]	Injected current on ISPSEL pin	± 5	
	Injected current on $\overline{\text{RESET}}$ pin	± 5	
	Injected current on OSC1 and OSC2 pins	± 5	
	Injected current on any other pin [5)]	± 5	
$\Sigma I_{INJ(PIN)}$ [2)]	Total injected current (sum of all I/O and control pins) [5)]	± 20	

13.2.3 Thermal Characteristics

Symbol	Ratings	Value	Unit
T_{STG}	Storage temperature range	-65 to +150	°C
T_J	Maximum junction temperature (see Table 21, “THERMAL CHARACTERISTICS,” on page 121)		

Notes:

1. Directly connecting the $\overline{\text{RESET}}$ and I/O pins to V_{DD} or V_{SS} could damage the device if an unintentional internal reset is generated or an unexpected change of the I/O configuration occurs (for example, due to a corrupted program counter). To guarantee safe operation, this connection has to be done through a pull-up or pull-down resistor (typical: 4.7kΩ for $\overline{\text{RESET}}$, 10kΩ for I/Os). Unused I/O pins must be tied in the same way to V_{DD} or V_{SS} according to their reset configuration.
2. When the current limitation is not possible, the V_{IN} absolute maximum rating must be respected, otherwise refer to $I_{INJ(PIN)}$ specification. A positive injection is induced by $V_{IN}>V_{DD}$ while a negative injection is induced by $V_{IN}<V_{SS}$.
3. All power (V_{DD}) and ground (V_{SS}) lines must always be connected to the external supply.
4. Negative injection disturbs the analog performance of the device. In particular, it induces leakage currents throughout the device including the analog inputs. To avoid undesirable effects on the analog functions, care must be taken:
- Analog input pins must have a negative injection less than 0.8 mA (assuming that the impedance of the analog voltage is lower than the specified limits)
- Pure digital pins must have a negative injection less than 1.6mA. In addition, it is recommended to inject the current as far as possible from the analog input pins.
5. When several inputs are submitted to a current injection, the maximum $\Sigma I_{INJ(PIN)}$ is the absolute sum of the positive and negative injected currents (instantaneous values). These results are based on characterisation with $\Sigma I_{INJ(PIN)}$ maximum current injection on four I/O port pins of the device.

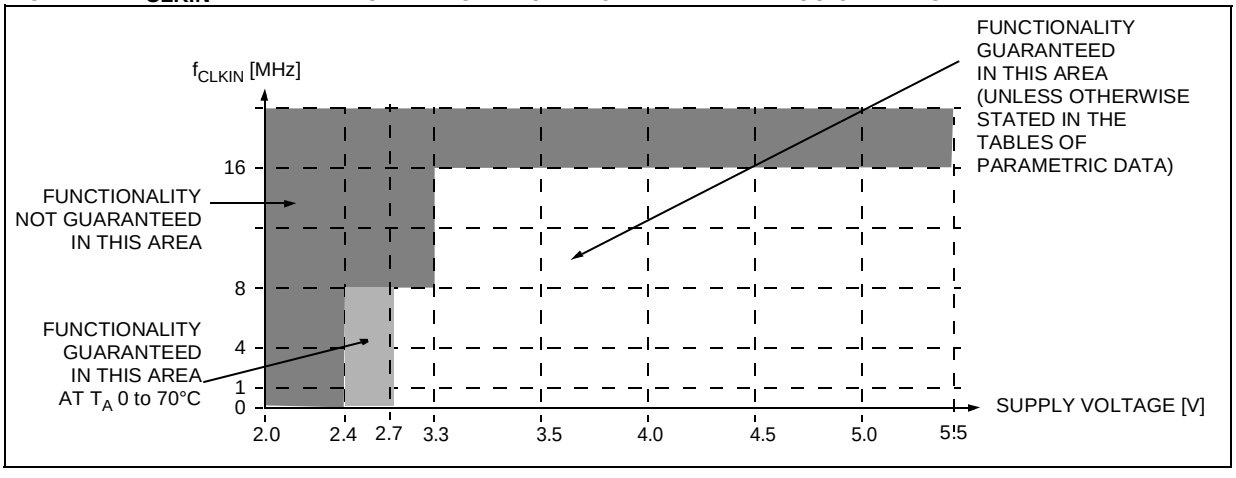
13.3 OPERATING CONDITIONS

13.3.1 General Operating Conditions: Suffix 6 Devices

T_A = -40 to +85°C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DD}	Supply voltage	f_{OSC} = 8 MHz. max., T_A = 0 to 70°C	2.4	5.5	V
		f_{OSC} = 8 MHz. max.	2.7	5.5	
		f_{OSC} = 16 MHz. max.	3.3	5.5	
f_{CLKIN}	External clock frequency on CLKIN pin	V_{DD}≥3.3V	0	16	MHz
		V_{DD}≥2.4V, T_A = 0 to +70°C	0	8	
		V_{DD}≥2.7V			

Figure 52. f_{CLKIN} Maximum Operating Frequency Versus V_{DD} Supply Voltage



13.3.2 Operating Conditions with Low Voltage Detector (LVD)

T_A = -40 to 125°C, unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{IT+(LVD)}$	Reset release threshold (V_{DD} rise)	High Threshold Med. Threshold Low Threshold	4.00[1)] 3.40 [1)] 2.65 [1)]	4.25 3.60 2.90	4.50 3.80 3.15	V
$V_{IT-(LVD)}$	Reset generation threshold (V_{DD} fall)	High Threshold Med. Threshold Low Threshold	3.80 3.20 2.40	4.05 3.40 2.70	4.30 [1)] 3.65 [1)] 2.90[1)]	
V_{hys}	LVD voltage threshold hysteresis	$V_{IT+(LVD)}$-$V_{IT-(LVD)}$		200		mV
Vt_{POR}	V_{DD} rise time rate [2)]		20		20000	µs/V
$t_{g(VDD)}$	Filtered glitch delay on V_{DD}	Not detected by the LVD			150	ns
$I_{DD(LVD)}$	LVD/AVD current consumption			245		µA

Note:

1. Not tested in production.

2. Not tested in production. The V_{DD} rise time rate condition is needed to insure a correct device power-on and LVD reset. When the V_{DD} slope is outside these values, the LVD may not ensure a proper reset of the MCU.

13.3.3 Auxiliary Voltage Detector (AVD) Thresholds

T_A = -40 to 125°C, unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{IT+(AVD)}$	1=>0 AVDF flag toggle threshold (V_{DD} rise)	High Threshold Med. Threshold Low Threshold	4.40[1)] 3.90[1)] 3.20[1)]	4.70 4.10 3.40	5.00 4.30 3.60	V
$V_{IT-(AVD)}$	0=>1 AVDF flag toggle threshold (V_{DD} fall)	High Threshold Med. Threshold Low Threshold	4.30 3.70 2.90	4.60 3.90 3.20	4.90[1)] 4.10[1)] 3.40[1)]	
V_{hys}	AVD voltage threshold hysteresis	$V_{IT+(AVD)}$-$V_{IT-(AVD)}$		150		mV
ΔV_{IT-}	Voltage drop between AVD flag set and LVD reset activation	V_{DD} fall		0.45		V

Note:

1. Not tested in production.

13.3.4 Internal RC Oscillator and PLL

The ST7 internal clock can be supplied by an internal RC oscillator and PLL (selectable by option byte).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DD(RC)}$	Internal RC Oscillator operating voltage		2.4		5.5	V
$V_{DD(x4PLL)}$	x4 PLL operating voltage		2.4		3.3	
$V_{DD(x8PLL)}$	x8 PLL operating voltage		3.3		5.5	
$t_{STARTUP}$	PLL Startup time			60		PLL input clock (f_{PLL}) cycles

I/O PORT PIN CHARACTERISTICS (Cont'd)

Figure 80. Typical V_{DD}-V_{OH} at V_{DD}=2.4V

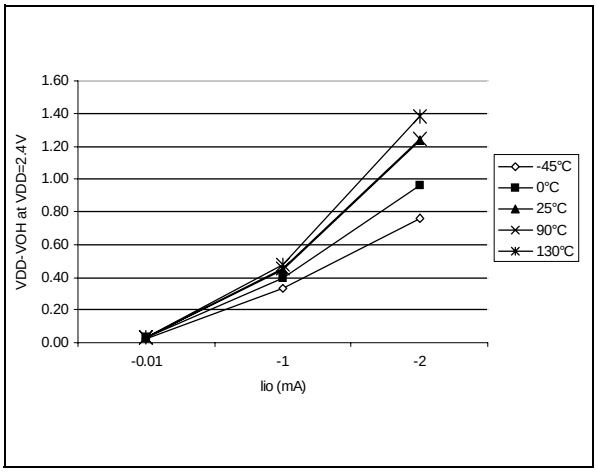


Figure 81. Typical V_{DD}-V_{OH} at V_{DD}=2.7V

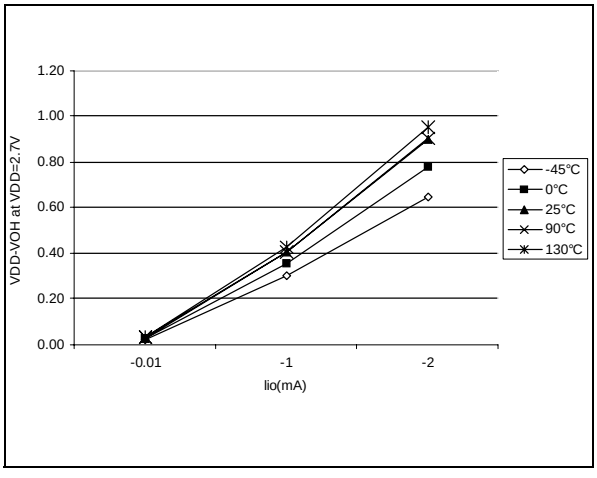


Figure 84. Typical V_{DD}-V_{OH} at V_{DD}=5V

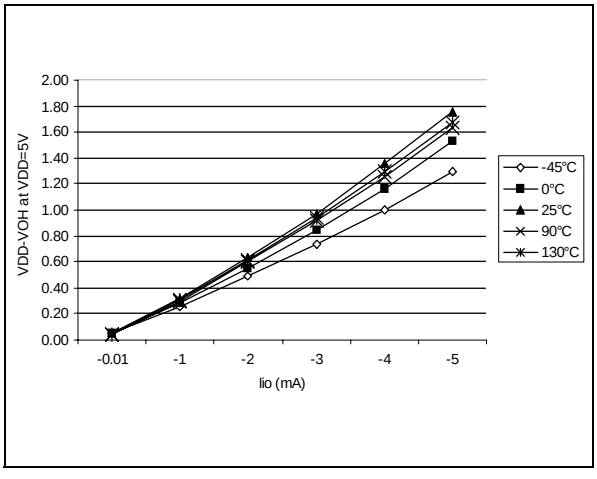


Figure 82. Typical V_{DD}-V_{OH} at V_{DD}=3V

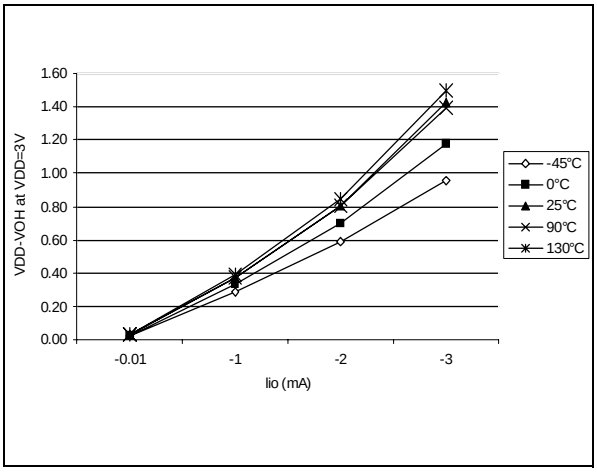
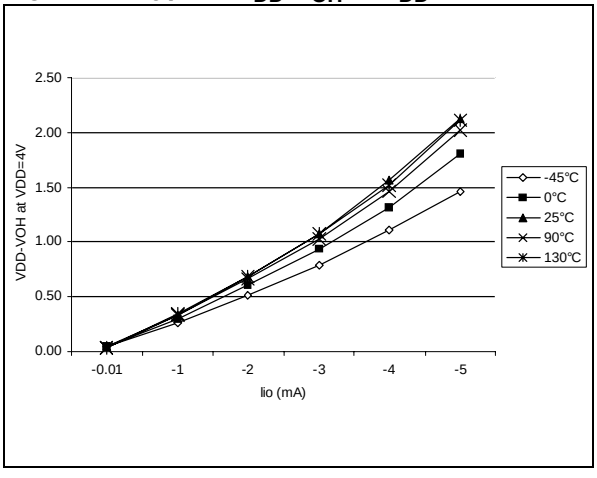


Figure 83. Typical V_{DD}-V_{OH} at V_{DD}=4V



13.10 COMMUNICATION INTERFACE CHARACTERISTICS

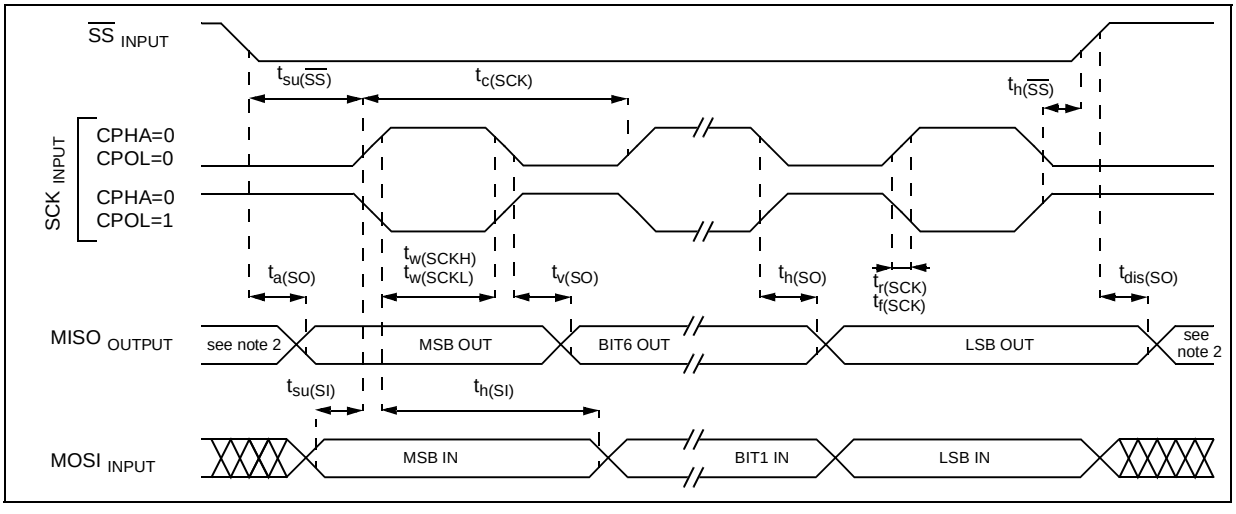
13.10.1 SPI - Serial Peripheral Interface

Subject to general operating conditions for V_{DD}, f_{OSC}, and T_A unless otherwise specified.

Refer to I/O port characteristics for more details on the input/output alternate function characteristics (SS, SCK, MOSI, MISO).

Symbol	Parameter	Conditions	Min	Max	Unit
f_{SCK} $1/t_{c(SCK)}$	SPI clock frequency	Master f_{CPU}=8MHz	$f_{CPU}/128$ 0.0625	$f_{CPU}/42$	MHz
		Slave f_{CPU}=8MHz	0	$f_{CPU}/24$	
$t_{r(SCK)}$ $t_{f(SCK)}$	SPI clock rise and fall time		see I/O port pin description		
$t_{su(\overline{SS})}$	$\overline{SS}$ setup time	Slave	120		ns
$t_{h(\overline{SS})}$	$\overline{SS}$ hold time	Slave	120		
$t_{w(SCKH)}$ $t_{w(SCKL)}$	SCK high and low time	Master Slave	100 90		
$t_{su(MI)}$ $t_{su(SI)}$	Data input setup time	Master Slave	100 100		
$t_{h(MI)}$ $t_{h(SI)}$	Data input hold time	Master Slave	100 100		
$t_{a(SO)}$	Data output access time	Slave	0	120	
$t_{dis(SO)}$	Data output disable time	Slave		240	
$t_{v(SO)}$	Data output valid time	Slave (after enable edge)		120	
$t_{h(SO)}$	Data output hold time		0		
$t_{v(MO)}$	Data output valid time	Master (before capture edge)	0.25		t_{CPU}
$t_{h(MO)}$	Data output hold time		0.25		

Figure 89. SPI Slave Timing Diagram with CPHA=0 3)



Notes:

1. Data based on design simulation and/or characterisation results, not tested in production.
2. When no communication is on-going the data output line of the SPI (MOSI in master mode, MISO in slave mode) has its alternate function capability released. In this case, the pin status depends on the I/O port configuration.
3. Measurement points are done at CMOS levels: $0.3xV_{DD}$ and $0.7xV_{DD}$.

15 DEVICE CONFIGURATION AND ORDERING INFORMATION

Each device is available for production in a user programmable version (FLASH). FLASH devices are shipped to customers with a default content (FFh). This implies that FLASH devices have to be configured by the customer using the Option Bytes.

15.1 OPTION BYTES

The two option bytes allow the hardware configuration of the microcontroller to be selected.

The option bytes can be accessed only in programming mode (for example using a standard ST7 programming tool).

OPTION BYTE 0

OPT7 = Reserved, must always be 1.

OPT6:4 = **OSCRANGE[2:0]** *Oscillator range*
When the internal RC oscillator is not selected (Option OSC=1), these option bits select the range of the resonator oscillator current source or the external clock source.

			OSCRANGE		
			2	**1**	**0**
Typ. frequency range with Resonator	LP	1~2MHz	0	0	0
	MP	2~4MHz	0	0	1
	MS	4~8MHz	0	1	0
	HS	8~16MHz	0	1	1
	VLP	32.768kHz	1	0	0
External Clock source: CLKIN	on OSC1		1	0	1
	on PB4		1	1	1
Reserved			1	1	0

Note: When the internal RC oscillator is selected, the OSCRANGE option bits must be kept at their default value in order to select the 256 clock cycle delay (see Section 7.5).

OPT3:2 = **SEC[1:0]** *Sector 0 size definition*
These option bits indicate the size of sector 0 according to the following table.

Sector 0 Size	SEC1	SEC0
0.5k	0	0
1k	0	1
2k	1	0
4k	1	1

OPT1 = **FMP_R** *Read-out protection*
This option indicates if the FLASH program memory and Data EEPROM is protected against piracy. The read-out protection blocks access to the program and data areas in any mode except user mode and IAP mode. Erasing the option bytes when the FMP_R option is selected will cause the whole memory to be erased first and the device can be reprogrammed. Refer to the ST7 Flash Programming Reference Manual and section 4.5 on page 14 for more details
0: Read-out protection off
1: Read-out protection on

OPT0 = **FMP_W** *FLASH write protection*
This option indicates if the FLASH program memory is write protected.
Warning: When this option is selected, the program memory (and the option bit itself) can never be erased or programmed again.
0: Write protection off
1: Write protection on

	OPTION BYTE 0								OPTION BYTE 1							
	7							0	7							0
	Res.	OSCRANGE 2:0			SEC1	SEC0	FMP R	FMP W	PLL x4x8	PLL OFF	PLL32 OFF	OSC	LVD1	LVD0	WDG SW	WDG HALT
Default Value	1	1	1	1	1	1	0	0	1	1	1	0	1	1	1	1

IDENTIFICATION	DESCRIPTION
AN 982	USING ST7 WITH CERAMIC RESONATOR
AN1014	HOW TO MINIMIZE THE ST7 POWER CONSUMPTION
AN1015	SOFTWARE TECHNIQUES FOR IMPROVING MICROCONTROLLER EMC PERFORMANCE
AN1040	MONITORING THE VBUS SIGNAL FOR USB SELF-POWERED DEVICES
AN1070	ST7 CHECKSUM SELF-CHECKING CAPABILITY
AN1324	CALIBRATING THE RC OSCILLATOR OF THE ST7FLITE0 MCU USING THE MAINS
AN1477	EMULATED DATA EEPROM WITH XFLASH MEMORY
AN1502	EMULATED DATA EEPROM WITH ST7 HDFLASH MEMORY
AN1529	EXTENDING THE CURRENT & VOLTAGE CAPABILITY ON THE ST7265 VDDF SUPPLY
AN1530	ACCURATE TIMEBASE FOR LOW-COST ST7 APPLICATIONS WITH INTERNAL RC OSCILLATOR
PROGRAMMING AND TOOLS	
AN 978	KEY FEATURES OF THE STVD7 ST7 VISUAL DEBUG PACKAGE
AN 983	KEY FEATURES OF THE COSMIC ST7 C-COMPILER PACKAGE
AN 985	EXECUTING CODE IN ST7 RAM
AN 986	USING THE INDIRECT ADDRESSING MODE WITH ST7
AN 987	ST7 SERIAL TEST CONTROLLER PROGRAMMING
AN 988	STARTING WITH ST7 ASSEMBLY TOOL CHAIN
AN 989	GETTING STARTED WITH THE ST7 HIWARE C TOOLCHAIN
AN1039	ST7 MATH UTILITY ROUTINES
AN1064	WRITING OPTIMIZED HIWARE C LANGUAGE FOR ST7
AN1071	HALF DUPLEX USB-TO-SERIAL BRIDGE USING THE ST72611 USB MICROCONTROLLER
AN1106	TRANSLATING ASSEMBLY CODE FROM HC05 TO ST7
AN1179	PROGRAMMING ST7 FLASH MICROCONTROLLERS IN REMOTE ISP MODE (IN-SITU PROGRAMMING)
AN1446	USING THE ST72521 EMULATOR TO DEBUG A ST72324 TARGET APPLICATION
AN1478	PORTING AN ST7 PANTA PROJECT TO CODEWARRIOR IDE
AN1527	DEVELOPING A USB SMARTCARD READER WITH ST7SCR
AN1575	ON-BOARD PROGRAMMING METHODS FOR XFLASH AND HDFLASH ST7 MCUS

16 IMPORTANT NOTES

16.1 EXECUTION OF BTJX INSTRUCTION

When testing the address $FF with the "BTJT" or "BTJF" instructions, the CPU may perform an incorrect operation when the relative jump is negative and performs an address page change.

To avoid this issue, including when using a C compiler, it is recommended to never use address $00FF as a variable (using the linker parameter for example).

16.2 ADC CONVERSION SPURIOUS RESULTS

Spurious conversions occur with a rate lower than 50 per million. Such conversions happen when the measured voltage is just between 2 consecutive digital values.

Workaround

A software filter should be implemented to remove erratic conversion results whenever they may cause unwanted consequences.

16.3 A/ D CONVERTER ACCURACY FOR FIRST CONVERSION

When the ADC is enabled after being powered down (for example when waking up from HALT, ACTIVE-HALT or setting the ADON bit in the ADCCSR register), the first conversion (8-bit or 10-bit) accuracy does not meet the accuracy specified in the datasheet.

Workaround

In order to have the accuracy specified in the datasheet, the first conversion after a ADC switch-on has to be ignored.